

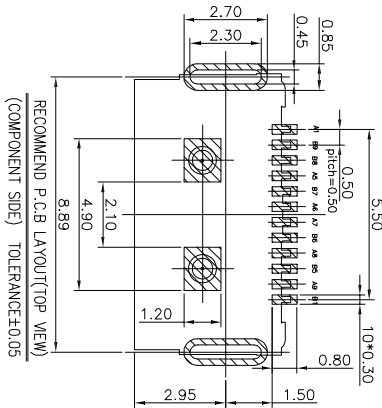
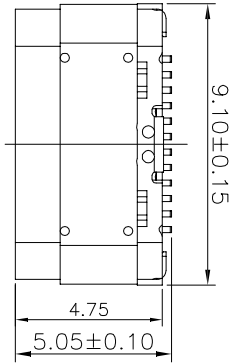
目錄 MAPX	變更內容 MODIFICATION	日期 DATE
A0	NEW	09-10-20

USB TYPE-C PIN ASSIGNMENTS

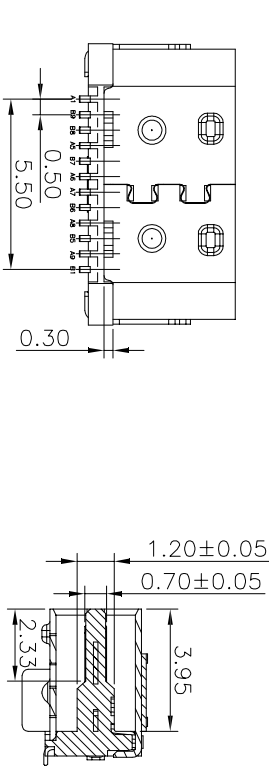
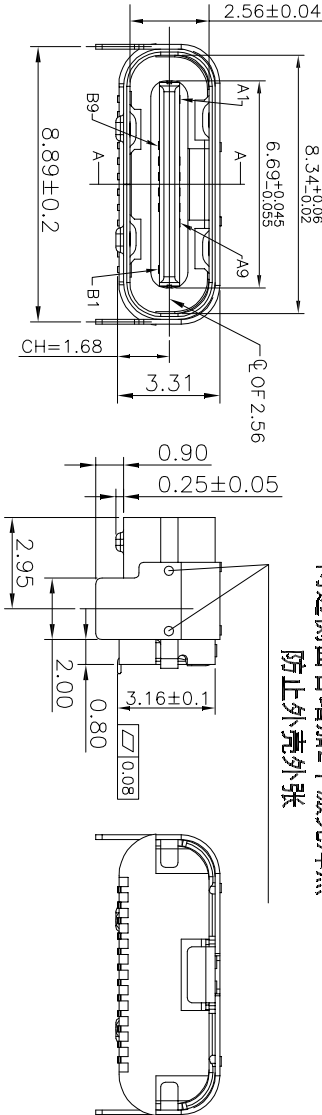
PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B9	VBUS
A5	CC1	B8	SRU2
A6	DP1	B7	DN2
A7	DM1	B6	DP2
A8	SBU1	B5	CC2
		B1	GND

NOTE:

- 1.MATERIAL SPECIFICATION:
1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
2.CONTACTS:COOPER ALLOY
3.MID PLATE: STAINLESS STEEL
4.FRONT SHELL: STAINLESS STEEL
- 2.PLATING SPECIFICATION:
2-1.CONTACTS:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
- 2-2.FRONT SHELL:
Ni 30u" MIN. UNDER PLATED OVER ALL.
- 2-3.MID PLATE:
CLEAR ONLY
- 3.MECHANICAL PERFORMANCE:
3-1.INSERTION FORCE: 0.5~2.0kgf.
3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
3-3.DURABILITY: 1000 CYCLES.
- 4.ELECTRICAL PERFORMANCE:
4-1. CURRENT RATING:5.0A
VOLTAGE RATING:5.0V
- 4-2. LCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LCR MAX. CHANGE OF ALL PINS: 10mΩ.
- 4-3.INSULATION RESISTANCE: 100MΩ MIN
- 4-4.DIELECTRIC WITHSTAND VOLTAGE:AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25C°~+85C°.
- 6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



两边侧面各增加2个激光焊点
防止外壳外胀



SECTION A-A
SCALE 1:1

产品图

PRODUCT CHART DWG

公差一览表

公差一览表	单位	制图	审核	日期	比例	日期	比例	日期	比例
TOLERANCE UNLESS OTHERWISE	UNITS	DRAWING	CHECK	DATE	SCALE	DATE	SCALE	DATE	SCALE
X	±0.30	X	±5°						
.X	±0.25	.X	±2°						
.XX	±0.30	.XX	±1°						
.XXX	±0.15	.XXX	±0.5°						

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